BigTwin SuperServer SYS-221BT-DNC8R



Key Applications

All-Flash Hyperconverged Infrastructure, All-Flash Storage Area Network, All-Flash Object Storage,

Key Features

- Socket E (LGA 4677) support 4th Gen Intel® Xeon® Scalable processors;
- Intel® C741;
- Up to 16 DIMMs ECC DDR5 Slots;
- Internal PCIe 4.0 x8 for 2 M.2 NVMe support onboard; 1 PCIe 5.0 x16 (LP) slot; 2 PCIe 5.0 x8 (LP) slot; Tool-less support; Optional M.2 NVMe Boot Controller via SCC-A2NM2241G3-B1;
- Network connectivity via AIOM (OCP 3.0 compliant);
- 12 hot-Swap 2.5" drive bays (2x PCle 5.0 NVMe and 10x PCle 4.0 NVMe/SAS);
 Built-in SAS3 Support via Broadcom 3816; IT Mode;
- 4 cooling fans per 2U enclosure, 16.5K RPM; Shared Cooling Design; Liquid Cooling Support;
- 2200W Redundant Power Supplies Titanium Level (96%+); Shared Power Design;



Form Factor	2U Rackmount Enclosure: 449 x 88 x 730mm (17.68" x 3.47" x 28.75") Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")
Processor	4th Gen Intel® Xeon® Scalable processors Dual Socket LGA 4677 (Socket E) supported Intel Xeon CPU Max Series with high bandwidth memory (HBM) (Supports up to 350W TDB CBUs (Airscaled)) Supports up to 350W TDB CBUs (Liquid Cooled))
Drive Bays	(Supports up to 350W TDP CPUs (Aircooled), Supports up to 350W TDP CPUs (Liquid Cooled)) 12x 2.5" hot-swap NVMe/SAS drive bays; Optional HBA support via SAS3816 AOC
Expansion Slots	2 PCIe 5.0 x8 LP slot(s) 1 PCIe 5.0 x16 LP slot(s)
On-Board Devices	SAS: SAS3 (12Gbps) via Broadcom® 3816 (IT mode) Chipset: Intel® C741 Network Connectivity: Via AIOM IPMI: Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
Input / Output	LAN: 1 RJ45 Dedicated BMC LAN port USB: 2 USB 3.1 port(s) (2 rear) Video: 1 VGA port(s) Others: 2x M.2 for boot drive or caching M.2 form factor: NVMe double-sided 22x110mm Note: Enterprise-grade M.2 only for caching application

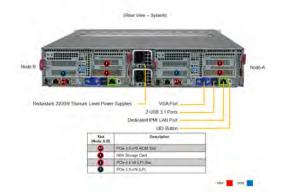
(Front Viva - System)



(Node A-B)	Description:
(P-(I)	2x25" Hot Steep NVMx Gard (CPUT/SAS Date Bays
(2)-(B)	2s 2.5" Hot Swap NVMe Gen4 (CPU1)/SAS Dine Bays .
0-8	8x 2.5' Hot-Swap NVMe Gen4 (CPU2)/SAS Dive Bays

CSE-217BD2-R2K22P

Chassis



System Cooling	4x 16.5K RPM Heavy Duty 8cm Fan(s) Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)
Power Supply	2200W Redundant Power Supplies with PMBus Dimension (W x H x L): 45 x 40 x 480 mm
System BIOS	BIOS Type: AMI 32MB Flash ROM
Management	SuperDoctor® 5; Watch Dog; SUM; IPMI 2.0; KVM with dedicated LAN; SPM; Intel® Node Manager; SSM; SuperCloud Composer; Supemicro Out of Band (OOB) License (Included per Node)
PC Health Monitoring	FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment CPU: Monitors for CPU Cores, Chipset Voltages, Memory. 8+4 Phase-switching voltage regulator
Dimensions and Weight	Height: 3.47" (88 mm) Width: 17.68" (449 mm) Depth: 28.75" (730 mm) Gross Weight: 80.7 lbs (36.6 kg) Net Weight: 55.1 lbs (25 kg) Packaging: 9.76" (H) x 24.65" (W) x 45.28" (D) Available Color: Black front & silver body
Operating Environment	ROHS: RoHS Compliant Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -40°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 90% (Non-Condensing) Non-operating Relative Humidity: 5% to 95% (Non-Condensing)
Motherboard	Super X13DET-B